

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

*Stenson*  
*#5/9*  
*9-20-01*

In re the Application of

Nobuaki HASHIMOTO

Application No.: US National Stage of PCT/JP00/06767

Filed: May 30, 2001

Docket No.: 109681

For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME,  
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office  
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 7, 10, 17-19, 27 and 29 as follows:

Sub B3  
A1

7. (Amended) The semiconductor device as defined in claim 1,  
wherein a recognition hole is formed in the substrate at a position differing from the  
holes; and  
wherein a recognition pattern is formed over the recognition hole on the side of a  
surface of the substrate including the interconnecting pattern.

Sub B4  
A2

10. (Amended) The semiconductor device as defined in claim 1,  
wherein the conductive members are a plurality of layered bumps.

17. (Amended) The semiconductor device as defined in claim 1,  
wherein the semiconductor chip is mounted face-down to the substrate.

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18. (Amended) A circuit board over which is mounted the semiconductor device  
as defined in claim 1.